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(12) **United States Design Patent**
Liao et al.

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(45) **Date of Patent:** **** Dec. 9, 2008**

(54) **LINEAR TYPE LIGHT EMITTING DIODE ASSEMBLY WITH HEAT DISSIPATING MODULE**

D566,303 S * 4/2008 Uemoto et al. D26/24
D572,387 S * 7/2008 Uemoto et al. D26/24

* cited by examiner

(75) Inventors: **Hung-Ta Liao**, Taipei County (TW);
Pao-Shen Chen, Taipei County (TW)

Primary Examiner—Marcus A. Jackson
(74) *Attorney, Agent, or Firm*—Rosenberg, Klein & Lee

(73) Assignee: **Edison Opto Corporation**, Taipei Hsien (TW)

(57) **CLAIM**

The ornamental design for a linear type light emitting diode assembly with heat dissipating module, as shown and described.

(**) Term: **14 Years**

(21) Appl. No.: **29/306,153**

(22) Filed: **Apr. 3, 2008**

DESCRIPTION

(51) **LOC (8) Cl.** **26-04**

FIG. 1 is a perspective view of a linear type light emitting diode assembly with heat dissipating module showing our new design;

(52) **U.S. Cl.** **D26/2**

FIG. 2 is a front elevational view thereof;

(58) **Field of Classification Search** D26/1-4;

FIG. 3 is a rear elevational view thereof;

313/313, 315, 317, 318, 493; 315/52, 53,
315/56, 57, 58

FIG. 4 is a left side elevational view thereof;

See application file for complete search history.

FIG. 5 is a right side elevational view thereof;

(56) **References Cited**

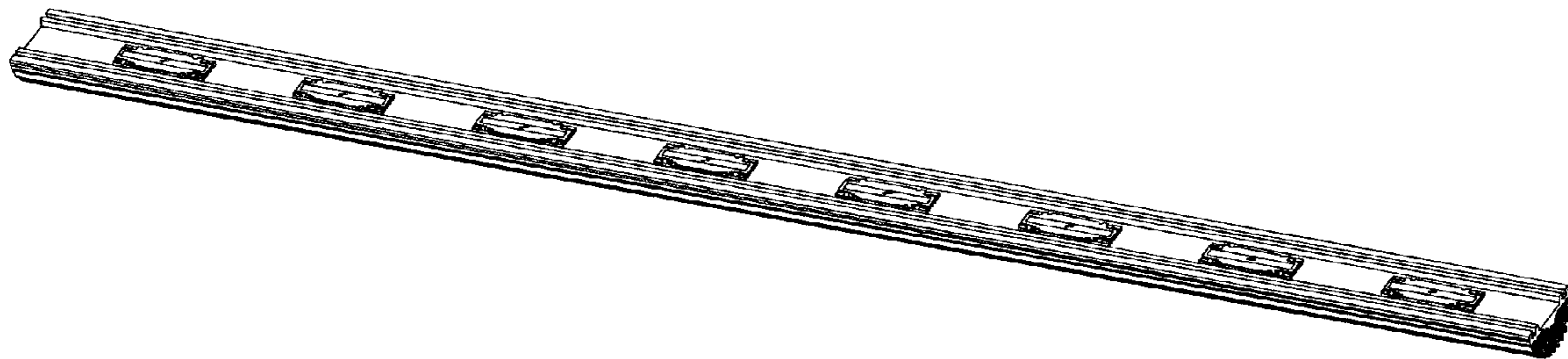
FIG. 6 is a bottom side elevational view thereof; and,

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FIG. 7 is a top side elevational view thereof.

D565,515 S * 4/2008 Chen D13/180
D565,753 S * 4/2008 Uemoto et al. D26/24

1 Claim, 6 Drawing Sheets



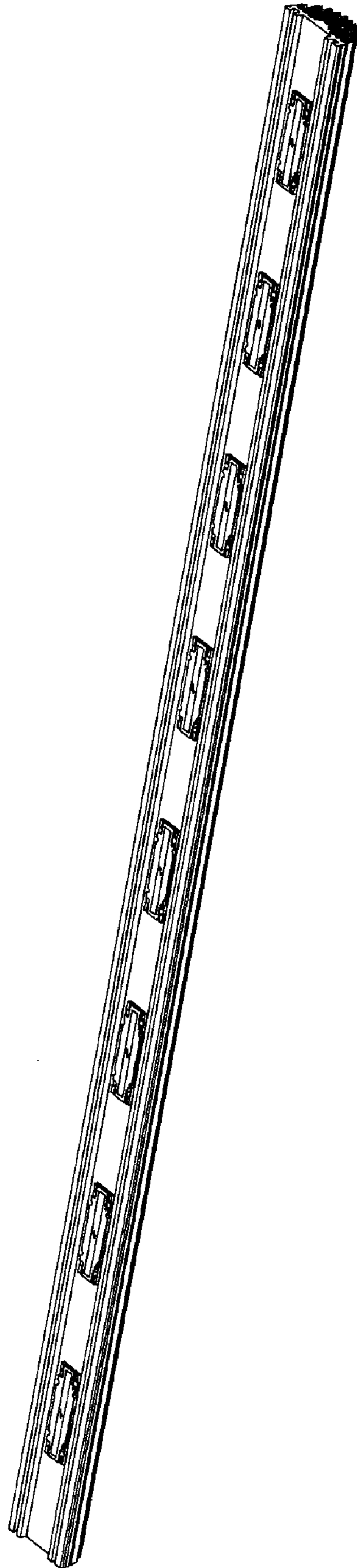


FIG.1

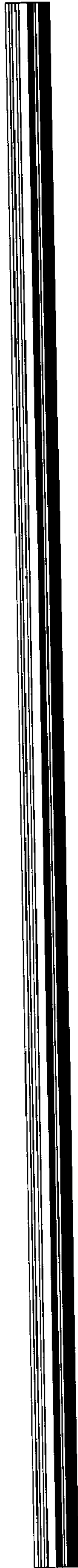


FIG.2



FIG.3

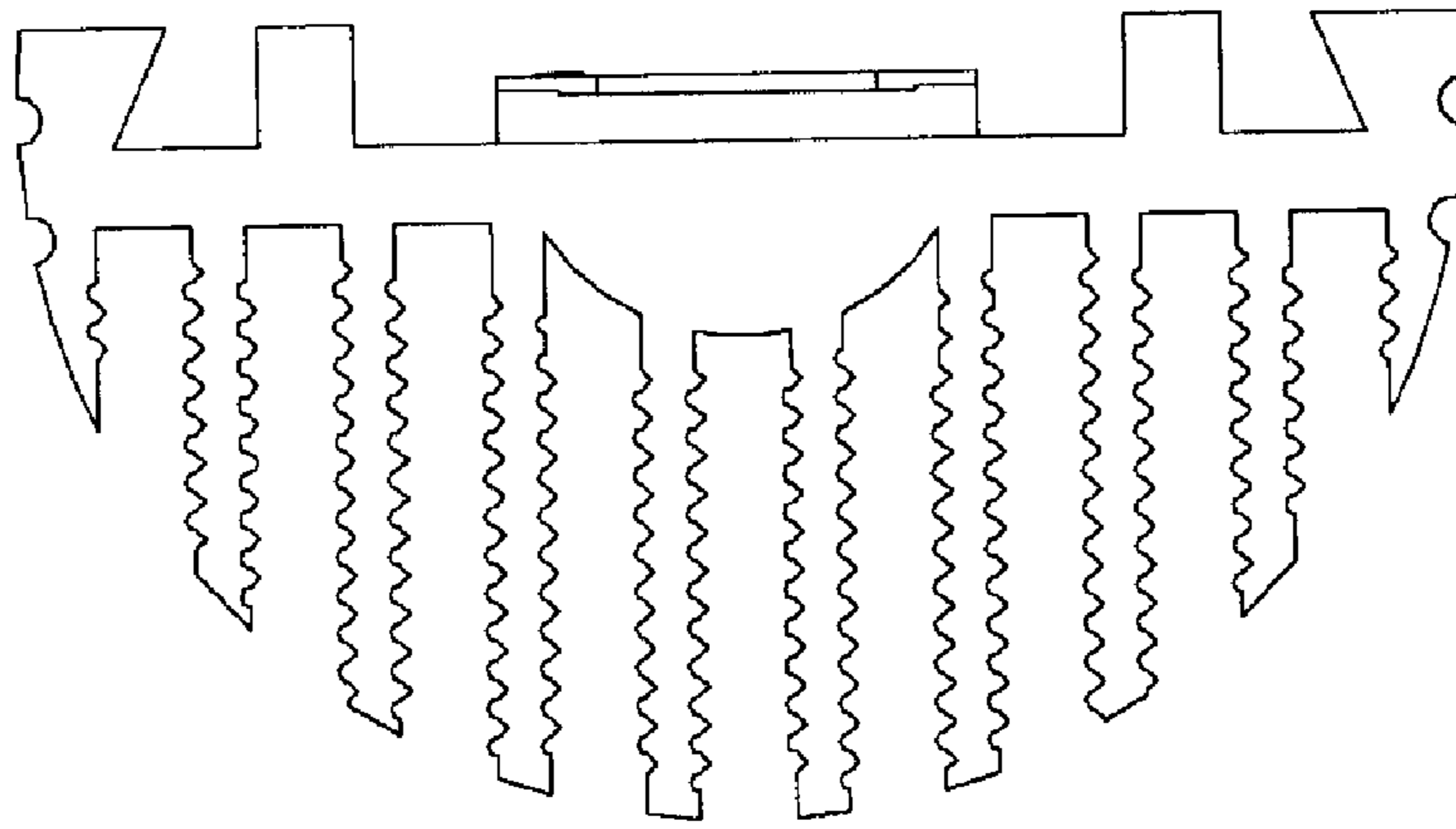


FIG. 4

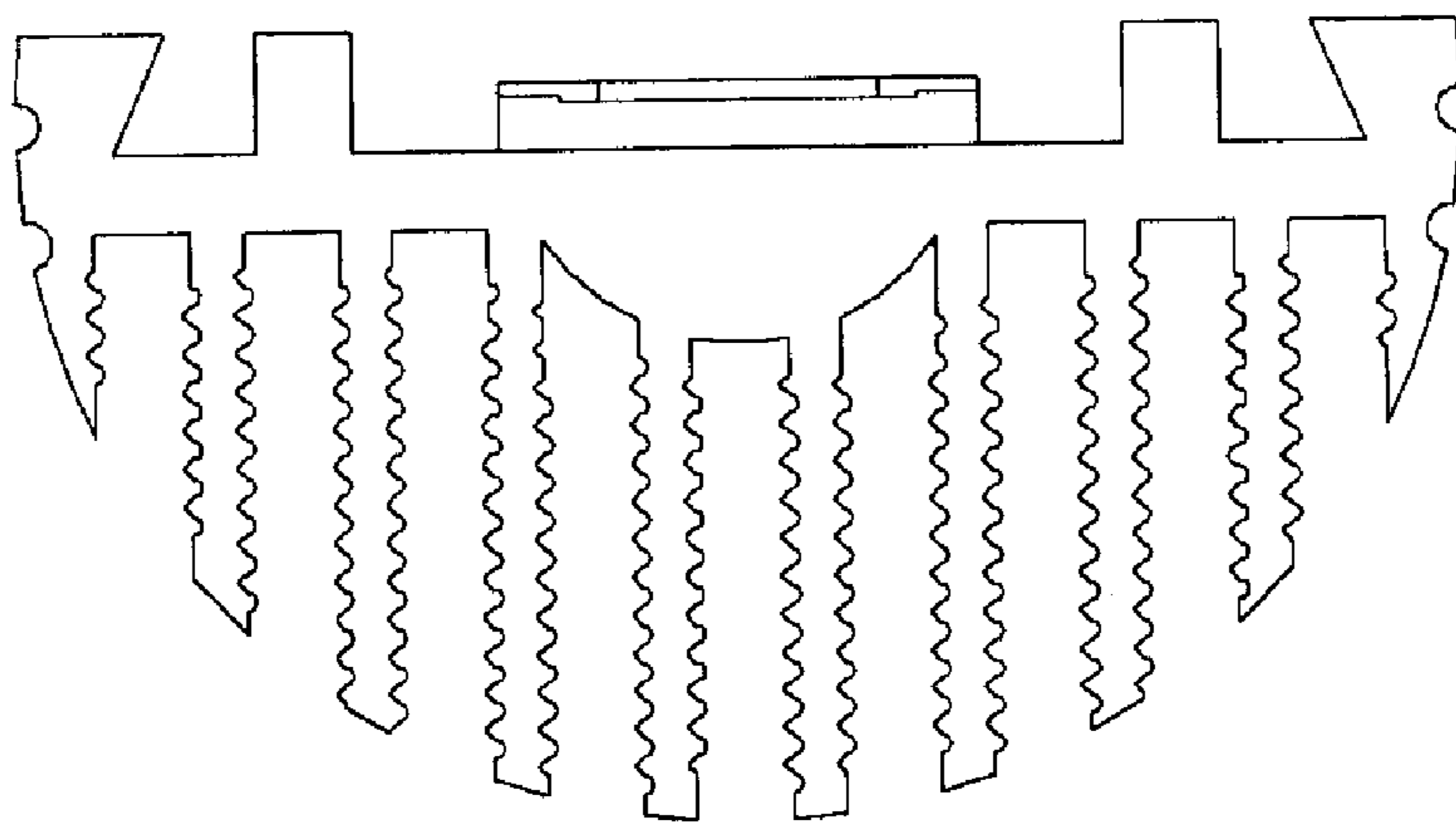


FIG. 5

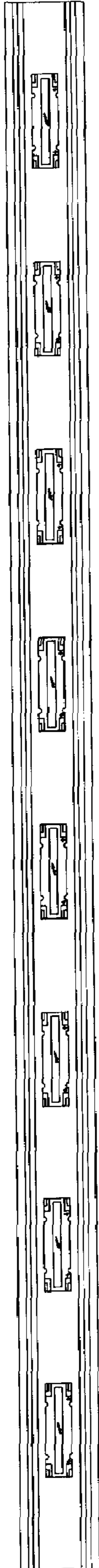


FIG. 6



FIG. 7